

# R1LP5256E Series

## 256Kb Advanced LPSRAM (32k word x 8bit)

R10DS0268EJ0200 Rev.2.00 2019.10.29

### **Description**

The R1LP5256E Series is a family of low voltage 256-Kbit static RAMs organized as 32,768-word by 8-bit, fabricated by Renesas's high-performance 0.15um CMOS and TFT technologies. The R1LP5256E Series has realized higher density, higher performance and low power consumption. The R1LP5256E Series is suitable for memory applications where a simple interfacing, battery operating and battery backup are the important design objectives. It has been packaged in 28-pin SOP and 28-pin TSOP.

#### **Features**

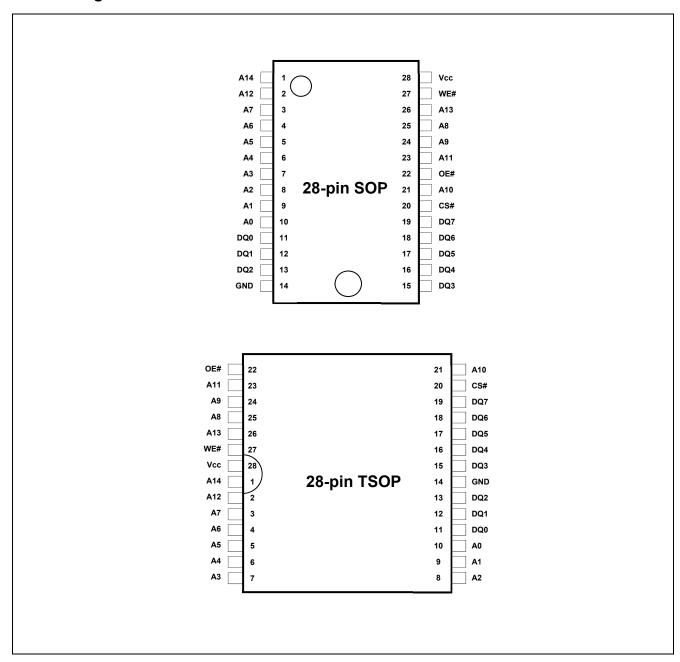
- Single 4.5V~5.5V power supply
- Small stand-by current: 0.6µA (5.0V, typical)
- No clocks, No refresh
- All inputs and outputs are TTL compatible.
- Easy memory expansion by CS#
- Common Data I/O
- Three-state outputs: OR-tie Capability
- OE# prevents data contention on the I/O bus

### **Ordering Information**

Orderable part name	Access time	Temperature range	Package	Shipping container	
R1LP5256ESP-5SI#B*			450-mil 28-pin	Tube (Magazine)	
R1LP5256ESP-5SI#S*	55 m -	-40 ~ +85°C	plastic SOP	Embossed tape	
R1LP5256ESA-5SI#B*	55 ns		-40 ~ +85 C	-40 ~ +85 C	8mm×13.4mm 28-pin
R1LP5256ESA-5SI#S*	LP5256ESA-5SI#S*	plastic TSOP	Embossed tape		

Note 1. \* = Revision code for Assembly site change, etc. (\* = 0, 1, etc.)

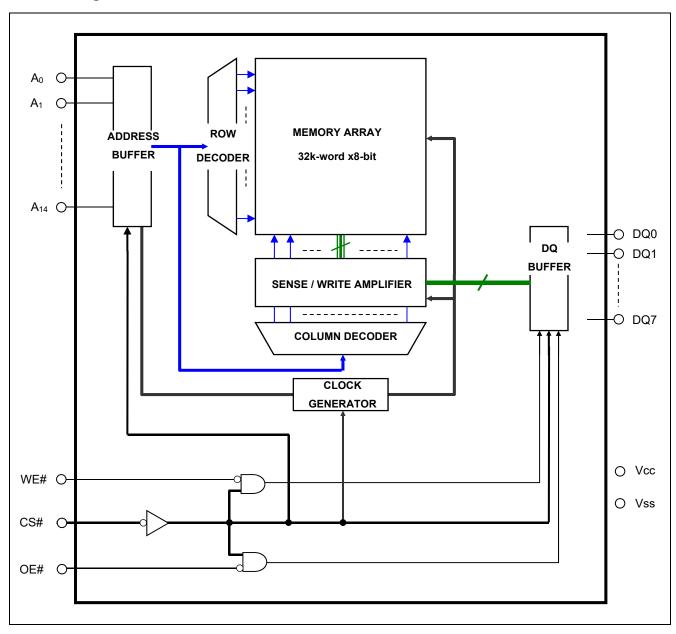
### **Pin Arrangement**



## **Pin Description**

Pin name	Function
Vcc	Power supply
Vss (GND)	Ground
A0 to A14	Address input
DQ0 to DQ7	Data input/output
CS#	Chip select
WE#	Write enable
OE#	Output enable

### **Block Diagram**



### **Operation Table**

CS#	WE#	OE#	DQ0~7	Operation
Н	Х	Х	High-Z	Stand-by
L	L	Х	Din	Write
L	Н	L	Dout	Read
L	Н	Н	High-Z	Output disable

Note 1. H:  $V_{IH}$  L: $V_{IL}$  X:  $V_{IH}$  or  $V_{IL}$ 

### **Absolute Maximum**

Parameter	Symbol	Value	unit
Power supply voltage relative to Vss	Vcc	-0.3 to +7.0	V
Terminal voltage on any pin relative to Vss	V <sub>T</sub>	-0.3*1 to Vcc+0.3*2	V
Power dissipation	P <sub>T</sub>	0.7	W
Operation temperature	Topr	-40 to +85	°C
Storage temperature range	Tstg	-65 to 150	°C
Storage temperature range under bias	Tbias	-40 to +85	°C

Note 1. –3.0V for pulse ≤ 30ns (full width at half maximum)

<sup>2.</sup> Maximum voltage is +7.0V.

### **DC Operating Conditions**

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage	Vcc	4.5	5.0	5.5	V	
	Vss	0	0	0	V	
Input high voltage	ViH	2.2	-	Vcc+0.3	V	
Input low voltage	VIL	-0.3	-	0.8	V	1
Ambient temperature range	Та	-40	-	+85	°C	

Note 1. -3.0V for pulse  $\leq 30$ ns (full width at half maximum)

#### **DC Characteristics**

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions		
Input leakage current		-	-	1	μΑ	Vin = Vss to Vcc		
Output leakage current	<b>I</b> LO	_	_	1	μА	CS# =V <sub>IH</sub> c	or OE# =V <sub>IH</sub> ,	
	1101			'	μιν	VI/O =Vss	to Vcc	
Average operating current	Icc <sub>1</sub>	_	25	35	mA		duty = 100%, $II/O = 0mA$ ,	
	1001		20	00	1117 \	CS# =V <sub>IL</sub> , (	Others = V <sub>IH</sub> /V <sub>IL</sub>	
						Cycle =1µs	s, duty =100%, II/O = 0mA,	
	Icc2	-	2	4	mA	CS# ≤ 0.2\	/,	
						V <sub>IH</sub> ≥ Vcc-0	.2V, V <sub>IL</sub> ≤ 0.2V	
Standby current	I <sub>SB</sub>	_	_	3	mA	CS# =V <sub>IH</sub> ,		
	128	_	_	3	ША	Others = V	ss to Vcc	
Standby current			0.6 <sup>*1</sup>	_	_	10500	Vin = Vss to Vcc,	
		-	0.6	2	μΑ	~+25°C	CS# ≥ Vcc-0.2V	
						. 4000		
	I <sub>SB1</sub>	-	-	3	μΑ	~+40°C		
		ISB1					7000	
		-	-	8	μΑ	~+70°C		
				40	_	.0500		
		-	-	10	μΑ	~+85°C		
Output high voltage	Vон	2.4	-	-	V	I <sub>OH</sub> = -1mA		
	V <sub>OH2</sub>	Vcc	_	_	V	Iон = -0.1m	nA	
	V 0112	- 0.5				.511 0.111		
Output low voltage	$V_{OL}$	-	-	0.4	V	I <sub>OL</sub> = 2mA		

Note 1. Typical parameter indicates the value for the center of distribution at 5.0V (Ta= 25°C), and not 100% tested.

### Capacitance

 $(Vcc = 4.5V \sim 5.5V, f = 1MHz, Ta = -40 \sim +85^{\circ}C)$ 

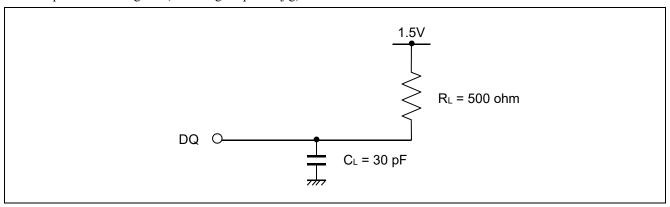
Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions	Note
Input capacitance	C in	-	-	6	pF	Vin =0V	1
Input / output capacitance	C 1/0	-	-	8	pF	VI/O =0V	1

Note 1. This parameter is sampled and not 100% tested.

#### **AC Characteristics**

Test Conditions (Vcc = 4.5V  $\sim 5.5$ V, Ta =  $-40 \sim +85$ °C)

- Input pulse levels: VIL = 0.6V, VIH = 2.4V
- Input rise and fall time: 5ns
- Input and output timing reference level: 1.5V
- Output load: See figures (Including scope and jig)



#### **Read Cycle**

Parameter	Symbol	Min.	Max.	Unit	Note
Read cycle time	t <sub>RC</sub>	55	-	ns	
Address access time	t <sub>AA</sub>	-	55	ns	
Chip select access time	t <sub>ACS</sub>	-	55	ns	
Output enable to output valid	toE	-	30	ns	
Output hold from address change	tон	10	-	ns	
Chip select to output in low-Z	tcLz	5	-	ns	2,3
Output enable to output in low-Z	tolz	5	-	ns	2,3
Chip deselect to output in high-Z t <sub>CHZ</sub>		0	20	ns	1,2,3
Output disable to output in high-Z toHz		0	20	ns	1,2,3

#### **Write Cycle**

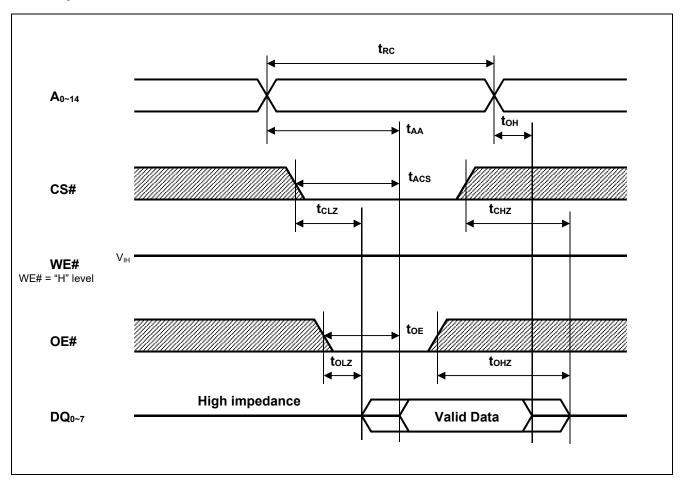
Parameter	Symbol	Min.	Max.	Unit	Note
Write cycle time	twc	55	-	ns	
Address valid to end of write	t <sub>AW</sub>	50	-	ns	
Chip select to end of write	tcw	50	-	ns	5
Write pulse width	twp	40	-	ns	4
Address setup time	t <sub>AS</sub>	0	-	ns	6
Write recovery time	twR	0	-	ns	7
Data to write time overlap	t <sub>DW</sub>	25	-	ns	
Data hold from write time	t₀н	0	-	ns	
Output enable from end of write	tow	5	-	ns	2
Output disable to output in high-Z toHz		0	20	ns	1,2
Write to output in high-Z		0	20	ns	1,2

Note

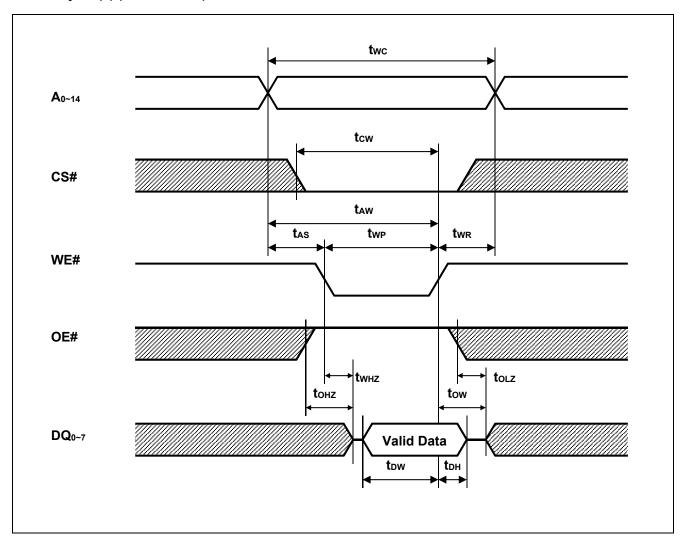
- 1.  $t_{CHZ}$ ,  $t_{OHZ}$  and  $t_{WHZ}$  are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.
- 2. This parameter is sampled and not 100% tested.
- 3. At any given temperature and voltage condition,  $t_{HZ}$  max is less than  $t_{LZ}$  min both for a given device and from device to device.
- 4. A write occurs during the overlap of a low CS#, a low WE#.
  - A write begins at the latest transition among CS# going low and WE# going low.
  - A write ends at the earliest transition among CS# going high and WE# going high.
  - $t_{\text{WP}}$  is measured from the beginning of write to the end of write.
- 5.  $t_{CW}$  is measured from the later of CS# going low to end of write.
- 6. tas is measured the address valid to the beginning of write.
- 7. twR is measured from the earliest of CS# or WE# going high to the end of write cycle.
- 8. Don't apply inverted phase signal externally when DQ pin is output mode.

### **Timing Waveforms**

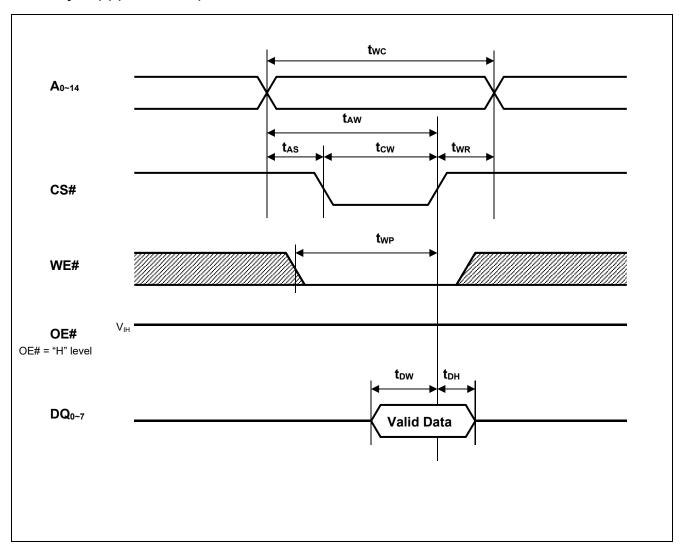
### Read Cycle



### Write Cycle (1) (WE# CLOCK)



### Write Cycle (2) (CS# CLOCK)

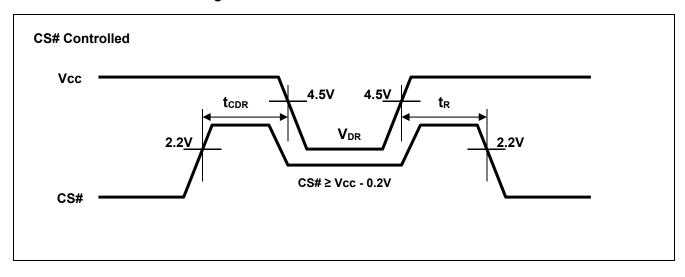


#### **Low Vcc Data Retention Characteristics**

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions*2		
V <sub>CC</sub> for data retention	$V_{DR}$	2.0	-	5.5	>	Vin ≥ 0V, CS# ≥ Vcc	c-0.2V	
	Iccor	-	0.6*1	2	μΑ	~+25°C		
Data retention current		-	1	3	μΑ	~+40°C	Vcc=3.0V, Vin ≥ 0V, CS# ≥ Vcc-0.2V	
		-	-	8	μΑ	~+70°C	C5# 2 VCC-0.2V	
		-	-	10	μΑ	~+85°C		
Chip deselect time to data retention	t <sub>CDR</sub>	0	-	-	ns	See retention waveform.		
Operation recovery time	t <sub>R</sub>	5	-	-	ms			

Note 1. Typical parameter indicates the value for the center of distribution at 3.0V (Ta= 25°C), and not 100% tested.

#### **Low Vcc Data Retention Timing Waveforms**



<sup>2.</sup> CS# controls address buffer, WE# buffer, OE# buffer and Din buffer. If CS# controls data retention mode, Vin levels (address, WE#, OE#, DQ) can be in the high impedance state.

Revision History	R1LP5256E Series Data Sheet

		Description				
Rev.	Date	Page	Summary			
1.00	2017.1.27	-	First Edition issued			
2.00	2019.10.29	p.1	p.1 Revised orderable part name information.			

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